



Click [here](#) for the 3D model.

Dimensions	
Chip Size	1812
L	4.52mm +/-0.3mm (0.178 in +/-0.012 in)
W	3.2mm +/-0.3mm (0.126 in +/-0.012 in)
T	2.79mm MAX (0.11 in MAX)
B	0.61mm +/-0.46mm (0.024 in +/-0.018 in)

  

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	42

General Information	
Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Gold
Failure Rate	N/A
Qualifications	MIL-PRF-32535 T-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.1 uF
Capacitance Tolerance	2%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.25% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)